

Title (en)

CONDUCTIVE MATERIAL COMPRISING AN Me-DLC HARD MATERIAL COATING

Title (de)

KUPFERHATLTIGER LEITWERKSTOFF MIT Me-DLC HARTSTOFFBESCHICHTUNG

Title (fr)

MATERIAU CONDUCTEUR A BASE DE CUIVRE PRESENTANT UN REVETEMENT EN MATERIAU DUR Me-DLC

Publication

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Application

**EP 05747049 A 20050615**

Priority

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Abstract (en)

[origin: WO2006005200A1] The invention relates to a conductive material consisting of an alloy that contains copper, for use as a plug-in or clip connection. Said material comprises a cover layer that is deposited on at least some sections of the contact surface, said layer consisting at least of a support layer and an adhesive layer. The anti-friction layer has a carbon content greater or less than 40 and less than or equal to 70 atomic percent.

IPC 8 full level

**C23C 16/26** (2006.01); **C23C 16/02** (2006.01); **H01H 1/02** (2006.01)

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DOCDB simple family (publication)

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